



# HTL294I

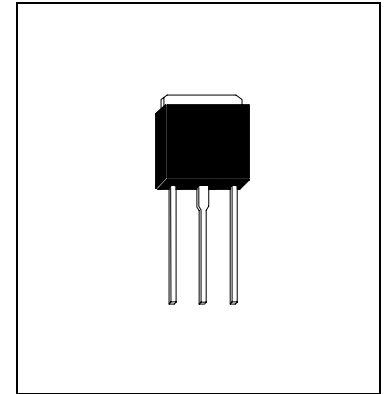
PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HTL294I is designed for application that requires high voltage.

## Features

- High Breakdown Voltage: 400(Min.) at IC=1mA
- High Current: IC=300mA at 25°C



## Absolute Maximum Ratings

- Maximum Temperatures  
 Storage Temperature ..... -55 ~ +150 °C  
 Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
 Total Power Dissipation (Ta=25°C) ..... 1 W
- Maximum Voltages and Currents (Ta=25°C)  
 VCBO Collector to Base Voltage ..... -400 V  
 VCEO Collector to Emitter Voltage ..... -400 V  
 VEBO Emitter to Base Voltage ..... -6 V  
 IC Collector Current ..... -250 mA

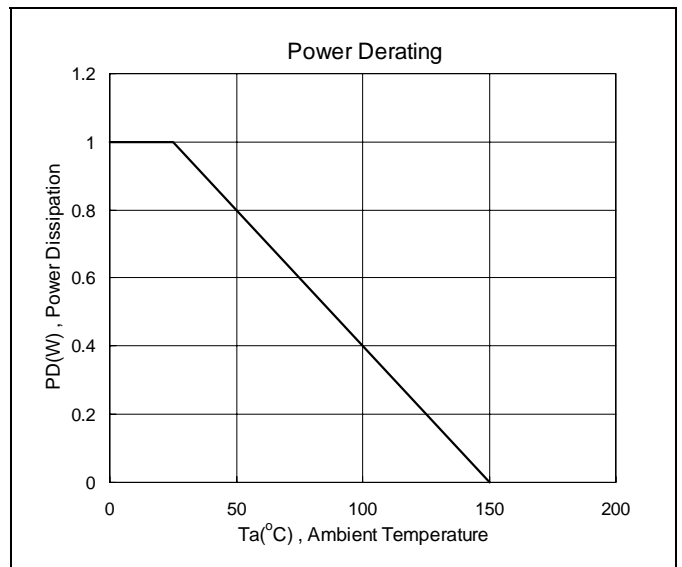
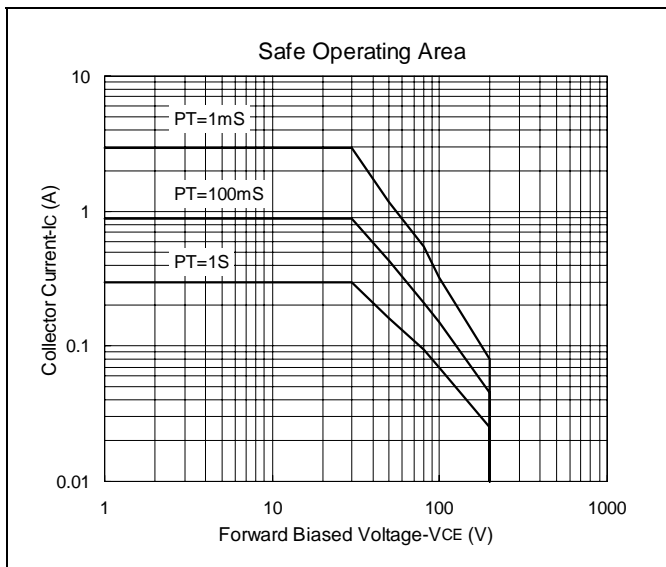
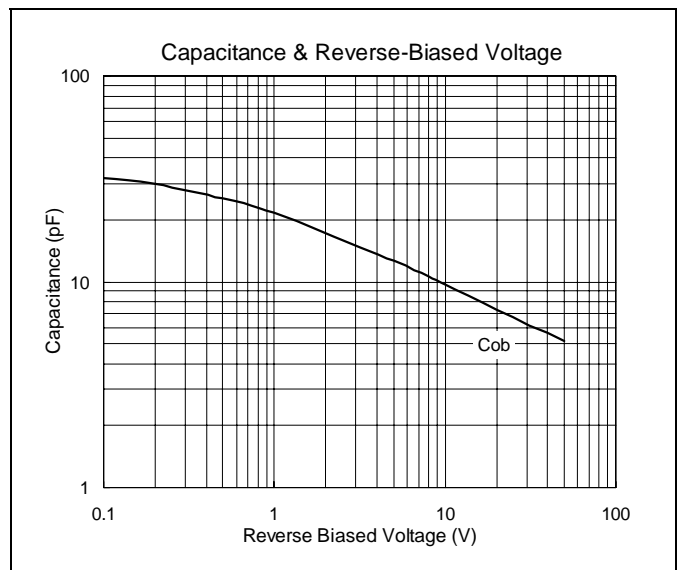
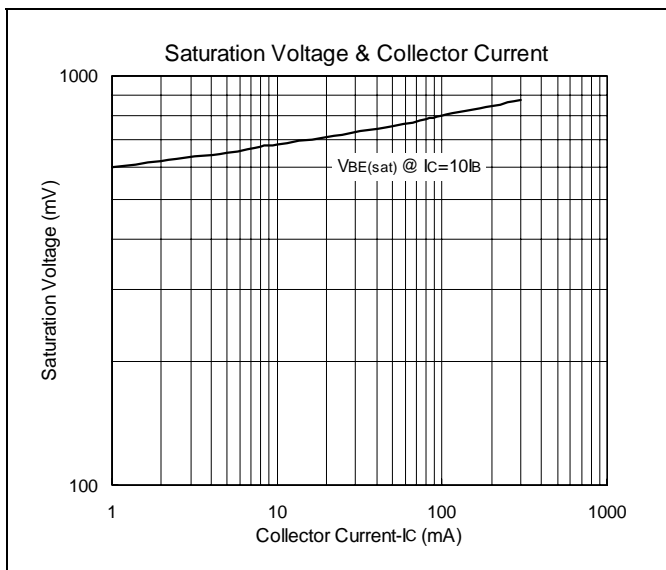
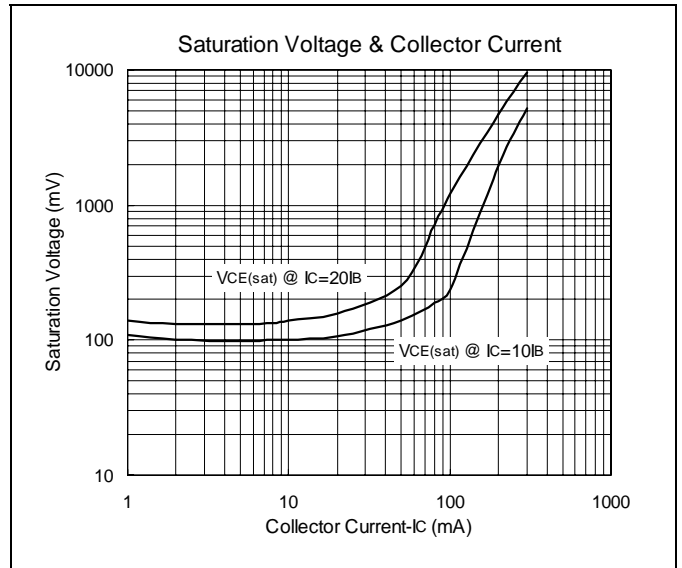
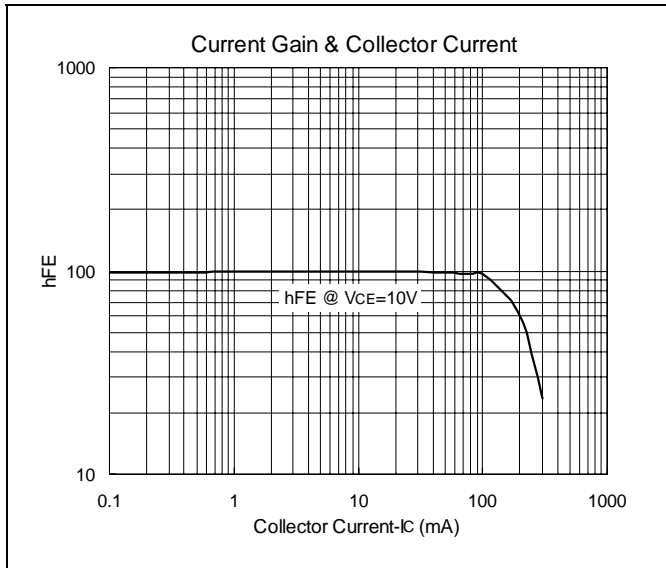
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-400	-	-	V	IC=-100uA, IE=0
BVCEO	-400	-	-	V	IC=-1mA, IB=0
BVEBO	-6	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-1	uA	VCB=-400V, IE=0
ICES	-	-	-10	uA	VCE=-400V, IC=0
IEBO	-	-	-0.2	uA	VEB=-6V, VBE=0
*VCE(sat)1	-	-	-300	mV	IC=-10mA, IB=-1mA
*VCE(sat)2	-	-	-500	mV	IC=-50mA, IB=-5mA
*VBE(sat)	-	-	-750	mV	IC=-10mA, IB=-1mA
*hFE1	50	-	-		VCE=-10V, IC=-1mA
*hFE2	60	-	250		VCE=-10V, IC=-20mA
*hFE3	50	-	-		VCE=-10V, IC=-80mA
ft	50	-	-	MHz	VCE=-20V, IE=-10mA, f=1MHz
Cob	-	-	30	pF	VCB=-20V, f=1MHz, IE=0

\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

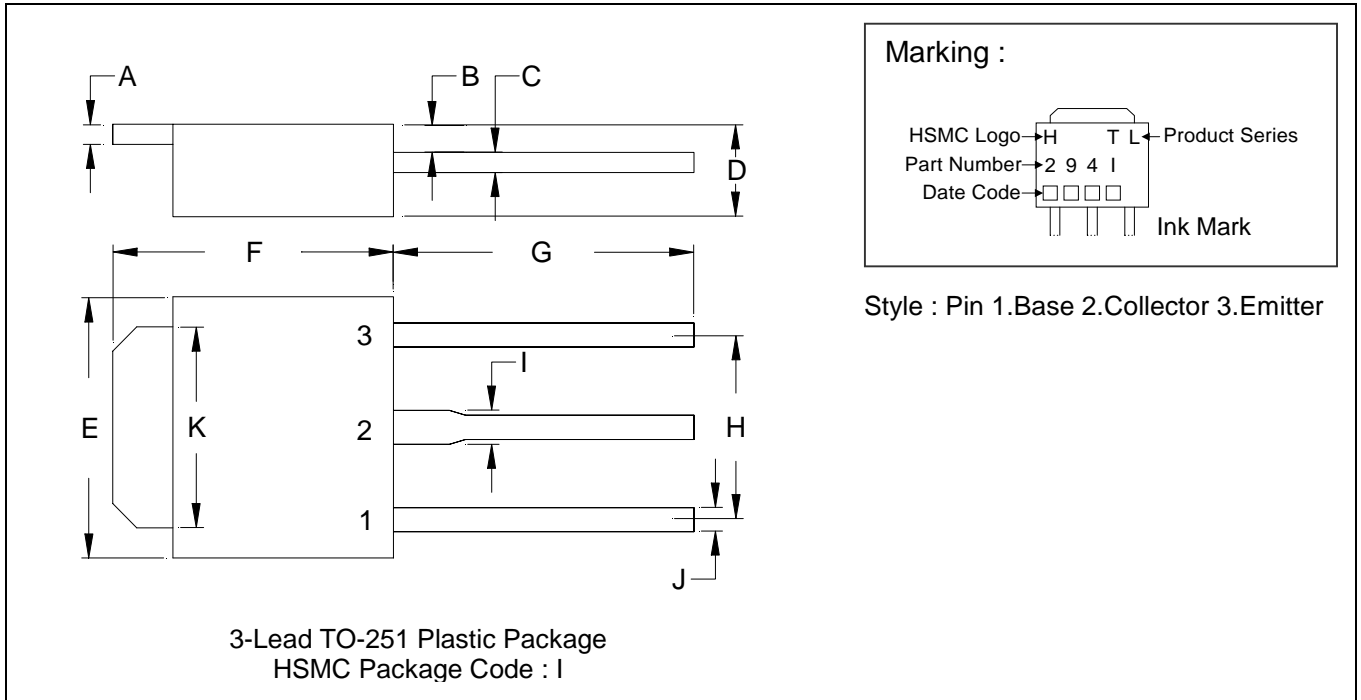


### Characteristics Curve





### TO-251 Dimension



\*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

**Notes :** 1.Dimension and tolerance based on our Spec. dated May. 24,1995.  
 2.Controlling dimension : millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material :**

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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